PCN # 2154A

DATE: July 6, 2021

EXPECTED PCN SHIP DATE: July 6, 2021



Quality Assurance 160 Rio Robles San Jose, CA 95134

www.maximintegrated.com

PROCESS CHANGE NOTICE	
X PRODUCT CHANGE NOTICE	
MAXIM INTEGRATED HEREBY ISSUES NOTIFICATION OF CHANGE THAT MAY AFFECT THE FOLLOWING CATEGORIES:	
□ DESIGN □ WAFER FAB ▼ ASSEMBL	Y
AFFECTED PRODUCT:	
Ordering P/N: (See PN listing XLS in PCN ZIP file)	
CHANGE FROM: - MAX20051AUD/MAX20053AUD	CHANGE TO: -
assembled at UTAC THAI LIMITED/ Thailand (UTL)	
Current bond wire material is Gold (Au).	The bond wire material will change to Copper (Pd coated Cu).
	Assembler UTL remains the same.
JUSTIFICATION: -	
The conversion to CuPd for these two devices will align with the other 16 devices in this product family already being manufactured	
with CuPd bond wire.	
UTL has been manufacturing CuPd wire TSSOP products for Maxim in mass production for several years.	
An AECQ-100 Reliability report is attached (ref. PCN 2154A_R28887_UTL CuPd).	
There are no changes to the Form/Fit/Function of the devices.	
TRACEABILITY: Maxim Integrated maintains full traceability by device marking, packaging labels and shipment documents.	
Maxim Integrated's Change Notification System is designed to keep our customer base apprised of major product, manufacturing, or facility improvements.	

or Nasser AliChaouche, PCN Coordinator
408-601-5660 / pcn.coordinator@maximintegrated.com

Nasser AliChaouche / PCN Coordinator

Nasser Ali Chronche

Document Title: Product Change Notice - Notification Only

For further information, please contact either of the people listed below.

Contact your local Maxim Integrated Company Representative

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